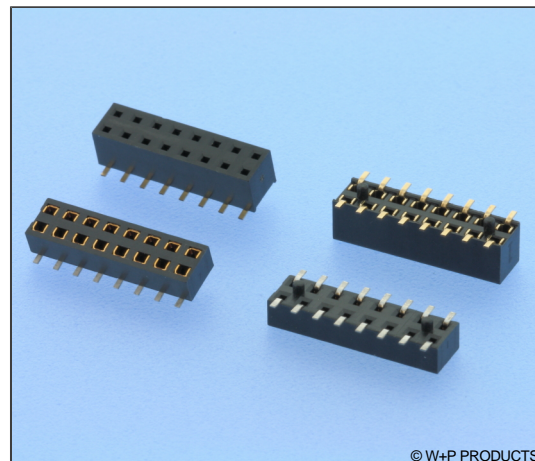


SMT-Buchsenleisten RM 2,00mm, stehend, 2-reihig – durchsteckbar

SMT Female Headers, 2.00mm Pitch, Vertical, Double Row – Pass Through

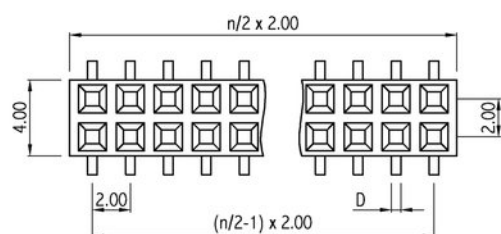
Technische Daten / Technical Data

Isolierkörper	Thermoplast, nach UL94 V-0
Insulator	Thermoplastic, rated UL94 V-0
Kontaktmaterial	Kupferlegierung
Contact Material	Copper alloy
Kontaktoberfläche	Lt. Oberflächenoptionen, über Ni (1,3 ... 2,5µm)
Contact Surface	Acc. to options (see below), over Ni (1.3 ... 2.5µm)
Durchgangswiderstand	< 20 mΩ
Contact Resistance	< 20 mΩ
Isolationswiderstand	> 1000 MΩ
Insulation Resistance	> 1000 MΩ
Spannungsfestigkeit	500 V AC
Test Voltage	500 V AC
Nennstrom	1 A
Current Rating	1 A
Temperaturbereich	-40 °C ... +125 °C
Temperature Range	-40 °C ... +125 °C
Verarbeitung	Reflow-Lötverfahren
Processing	Reflow soldering

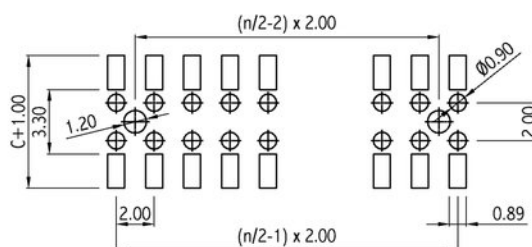
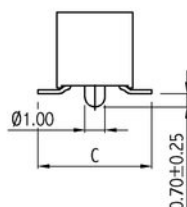
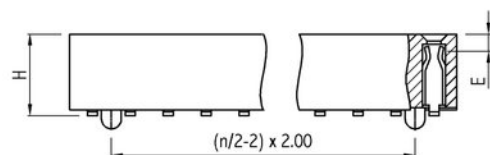


© W+P PRODUCTS

Doppelfederkontakte für
Vierkantstifte 0,50mm.
Dual beam contacts accept
0.50mm square pins.



Type -20- / -30-

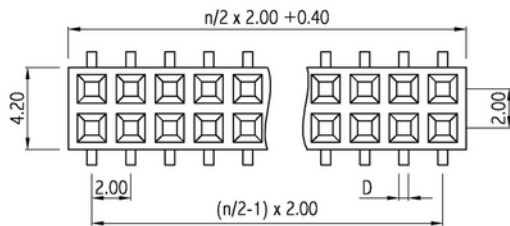
PCB Layout
(for all Types)

Type	H	C	D	E
20	4.30	6.00	0.50x0.20	1.20
30	3.70	6.40	0.15	

Series	Contacts*	Type*	Plating*	Locating Pegs*	Package*
7450	20 04-80 Type 20/30	20 20 H=4,3mm, Eingang oben H=4.3mm, top entry 30 H=3,7mm, Eingang oben H=3.7mm, top entry	00 00 Vergoldet Gold plated 50 Verzinnt Tin plated 60 Sel. Au/Sn Duplex plating	00 00 Ohne Pos.hilfen W/o loc. pegs 10 Mit Pos.hilfen (nur Type 20) With loc. pegs (only Type 20)	ST ST PPST PPTR

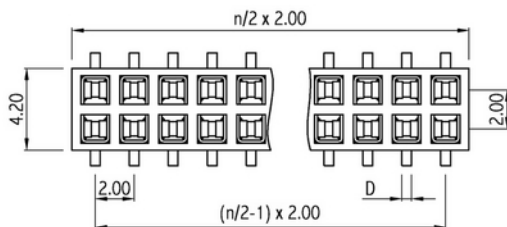
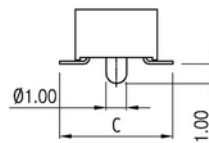
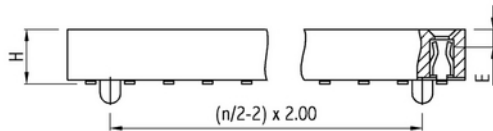
7450

SMT-Buchsenleisten RM 2,00mm, stehend, 2-reihig – durchsteckbar
SMT Female Headers, 2.00mm Pitch, Vertical, Double Row – Pass Through

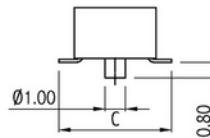
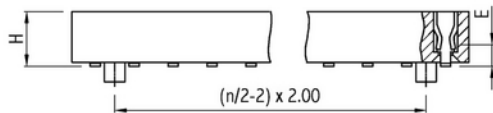


Type	H	C	D	E
10	2.80	5.80	0.50x0.15	0.90
11	2.80	5.80	0.50x0.15	1.10

Type -10-



Type -11-



Series	Contacts*	Type*	Plating*	Locating Pegs*	Packaging*
7450	22	10	00	10	ST
	04-80 Type 10/11	10 H=2,8mm, Eingang oben H=2.8mm, top entry 11 H=2,8mm, Eingang unten H=2.8mm, bottom entry	00 Vergoldet Gold plated 50 Verzinnt Tin plated 60 Sel. Au/Sn Duplex plating	00 Ohne Pos.hilfen W/o loc. pegs 10 Mit Pos.hilfen With loc. pegs	ST PPST PPTR

* Dies ist ein **Bestellbeispiel** -
 bitte durch Ihre Spezifikationen ersetzen.
 * This is an **order example** -
 please replace by your specifications.

Lieferformen / Packaging Options:

ST In Stangen ohne Pick&Place-Pads / In tubes w/o Pick&Place-Pads

PPST In Stangen mit P&P-Pads / In tubes with P&P-Pads

PPTR Tape & Reel mit P&P-Pads / Tape & Reel with P&P-Pads

Reflow-Lötempfehlung

Reflow Soldering Recommendation

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

Profileigenschaft	Kennwert
Temperatur Minimum T_{Smin}	150 °C
Temperatur Maximum T_{Smax}	200 °C
Dauer $T_{Smin} - T_{Smax}$	60 – 180s
Temperatur Lötbereich T_L	217 °C
Verweildauer oberhalb T_L	60 – 180s
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Höchsttemperatur T_P	260±5 °C
Dauer Höchsttemperatur	20 – 40s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Dauer 25 °C – Höchsttemperatur T_P	max. 8m

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

Profile Feature	Key Values
Minimum Temperature T_{Smin}	150 °C
Maximum Temperatur T_{Smax}	200 °C
Duration $T_{Smin} - T_{Smax}$	60 – 180s
Soldering Range Temperature T_L	217 °C
Duration above T_L	60 – 180s
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Peak Temperature T_P	260±5 °C
Duration Peak Temperature	20 – 40s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Duration 25°C - Peak Temp. T_P	max. 8min

